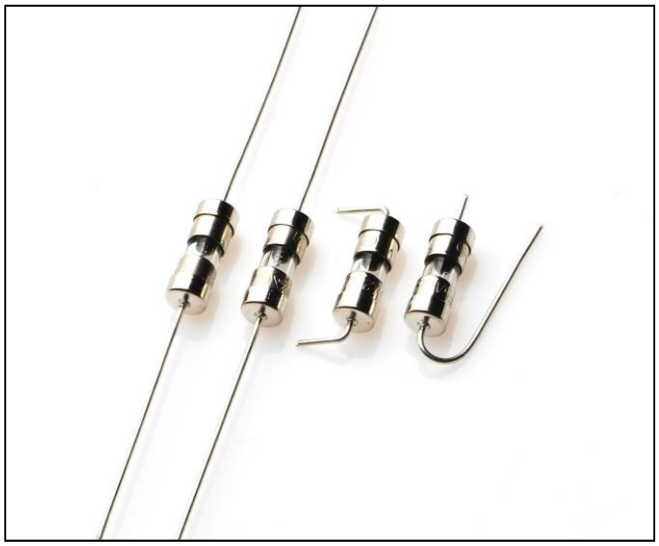
Type TDP

Time-Lag Micro Fuses Series



Description

TDP, Time-lag Type,250V rated designed in accordance to IEC 60127.3, GB/T9364.3,UL 248-14.

Features

- Lead-free
- Internationally approved
- Reduced PCB space requirements
- Direct solderable or plug-in versions
- Low internal resistance
- Shock safe casing
- Vibration resistant
- Halogen free

Applications

- Power supplies
- Battery Chargers
- Consumer Electronics
- Industrial Controllers
- Adapter

Agency Approvals.

Safety Agency	Agency File Number	Ampere Range Volt@I.R.ABILITY
	R 50510065	250mA~3.15A 35A@250V AC 4A~10A 10In@250V AC
	2020970207000097	250mA~3.15A 35A@250V AC 4A~6.3A 10In@250V AC
	SU05050-15004(≤800mA) SU05050-15005(3.15A~6.3A) SU05050-15006(1A~2.5A)	250mA~3.15A 35A@250V AC 4A~6.3A 10In@250V AC
	E485357	250 mA~15A 50A@125V AC 250mA~15A 50A@250V AC

Electrical Characteristics for Series

% of Ampere Rating	Opening Time
150%	1 Hour, Min
210%	2min,Max
275%	400ms Min,10s Max
400%	150ms Min,3s Max
1000%	20ms Min,150ms Max

Electrical Characteristic Specifications by Item

Catalog Number	Rated Current	Voltage Rating	Breaking Capacity	Melting Integral 10In min(A2S)	Agency Approvals			
					TUV	CCC	cULus	KC
TDP0250	250mA	125V AC 250V AC	50A@125V AC 50A@250V AC	0.300	●	●	●	●
TDP0315	315mA			0.556	●	●	●	●
TDP0400	400mA			0.928	●	●	●	●
TDP0500	500mA			1.125	●	●	●	●
TDP0630	630mA			2.183	●	●	●	●
TDP0800	800mA			3.584	●	●	●	●
TDP1100	1A			4.400	●	●	●	●
TDP1125	1.25A			7.031	●	●	●	●
TDP1160	1.6A			11.776	●	●	●	●
TDP1200	2A			23.200	●	●	●	●
TDP1250	2.5A			29.375	●	●	●	●
TDP1315	3.15A			50.605	●	●	●	●
TDP1400	4A			76.800	●	●	●	●
TDP1500	5A			132.500	●	●	●	●
TDP1630	6.3A			218.295	●	●	●	●
TDP1700	7A			220.000			●	
TDP1800	8A			276.000	●		●	
TDP2100	10A			369.000	●		●	

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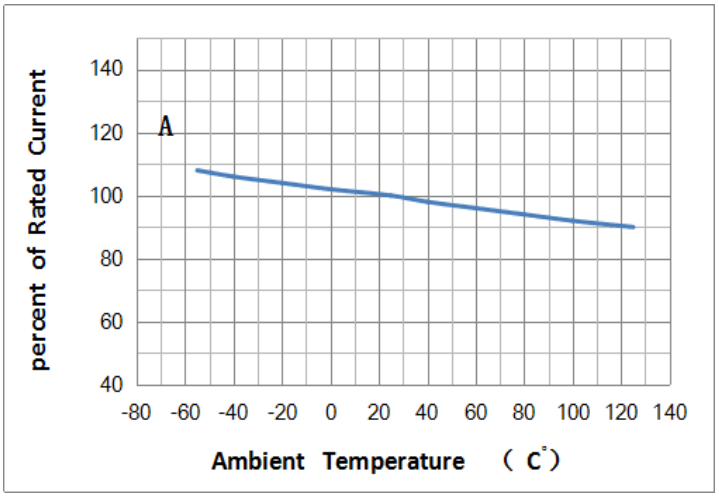
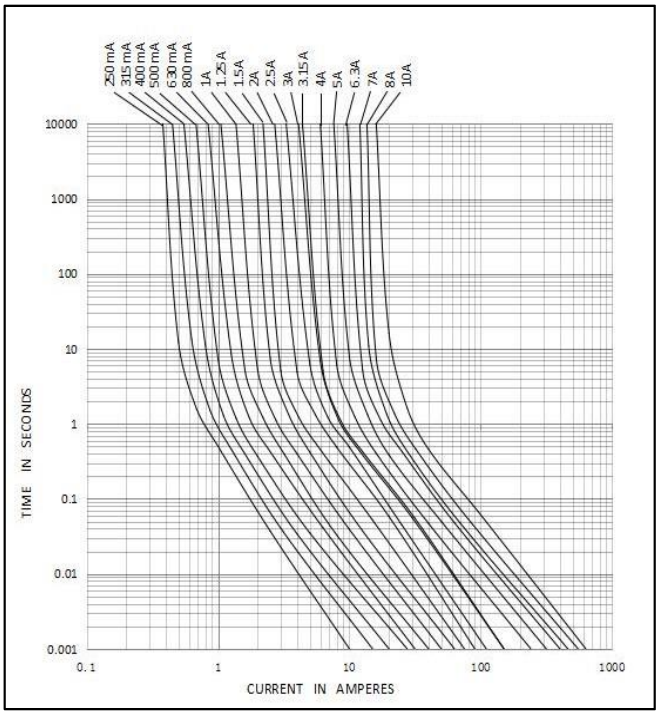
Temperature Re-rating Curve

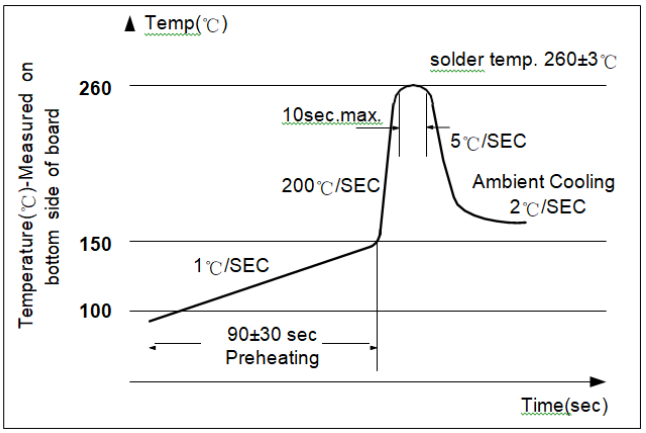


Average Time Current Curves



Soldering Parameters-Wave Soldering

Lead-Free Wave Soldering Profile	
Wave Soldering Parameter	
Average ramp-up rate	200℃/second
Heating rate during preheat	Typical 1-2℃/second Max 4℃/second
Final preheat temperature	Within 125℃ of Soldering temperature
Peak temperature	260℃
Time within +0/-5℃ of actual peak temperature	10 seconds
Ramp-down Rate	5℃/second max



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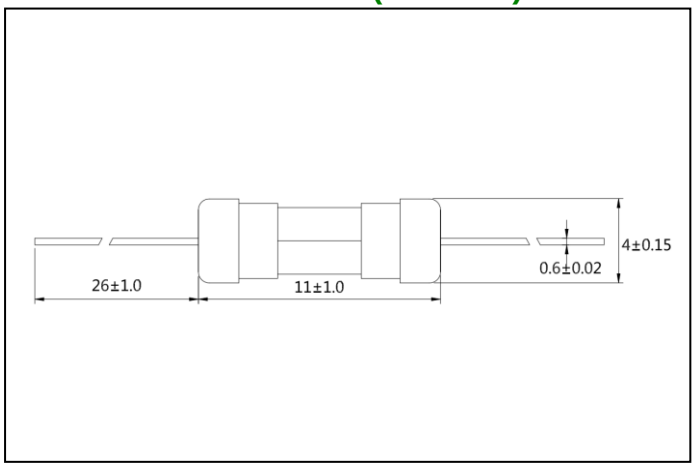
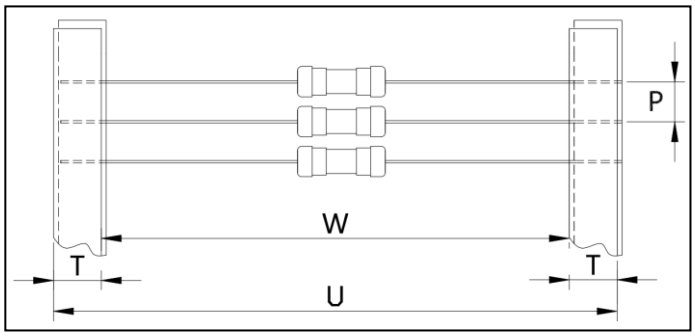
Product Characteristics

Materials	Glass Body Nickel Plated Brass Caps Lead Wire :Diameter 0.8mm、0.6mm
Lead Pull Strength	10 N(IEC 60068-2-21)
Soldering Parameters	260℃,≤10 sec.(wave) 350℃,≤3 sec.(soldering iron)
Soldering Heat Resistance	260℃,10 sec.(IEC 60068-2-20) 350℃,≤3 sec.(soldering iron)

Operating Temperature	-55℃ to +125℃(consider de-rating)
Climatic Category	-40℃ to +85℃/21 days (EN 60068-1, -2-1 ,-2-2, -2-78)
Stock Condition	+10℃ to +60℃ Relative humidity ≤75% yearly Average, without dew, maximum Value for 30 days-95%
Vibration Resistance	24 cycles at 15 min. each (EN 60068-2-6) 10-60 Hz at 0.75 mm amplitude 60-2000 Hz at 10 g acceleration

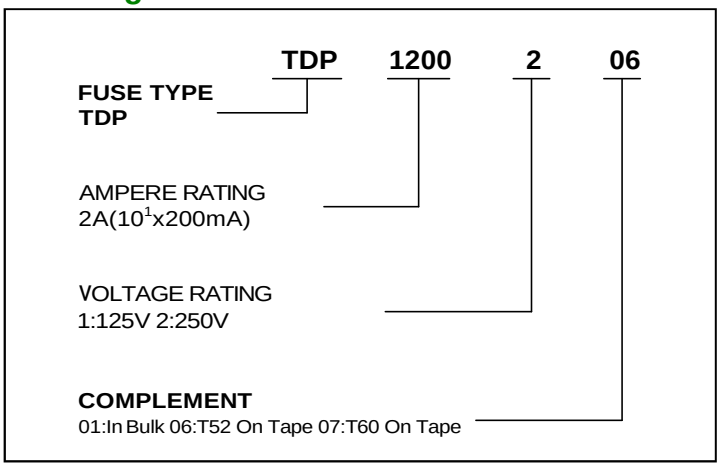
Mechanical Dimensions(Unit:mm)





编带标准	W	U	T	P
T52	52±1.5	65±1.5	6±0.2	5±0.05
T60	60±1.5	73.5±1.5	6±0.2	5±0.05

Ordering Information



Packaging

Packaging Option	Packaging Specification	Quantity
On Tape	N / A	1000pcs & 1500pcs
In Bulk	N / A	300pcs

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